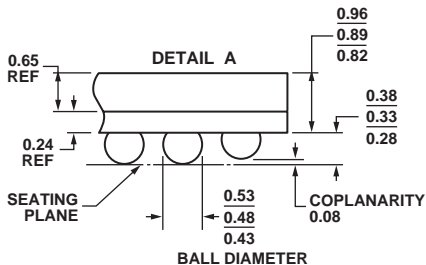
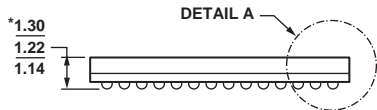
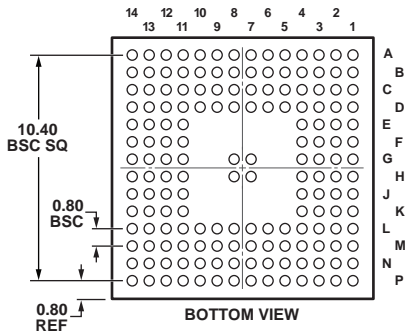
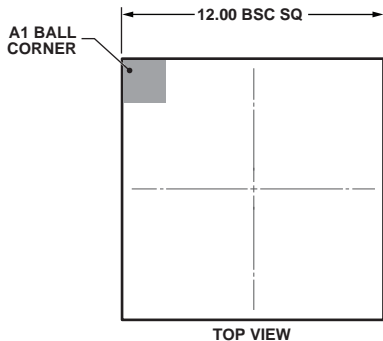


**164-Ball Chip Scale Package Ball Grid Array [CSP_BGA]
(BC-164-1)**

Dimensions shown in millimeters



*COMPLIANT TO JEDEC STANDARDS MO-219 WITH THE EXCEPTION TO PACKAGE HEIGHT.